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# NDB-M2658A Bluetooth Low Energy Module

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## 1 Device Overview

### 1.1 Description

Necdaz's single-mode Bluetooth module is a high-performance and low-power RF SOC module that incorporates the RS02A1 transceiver chip with super low power consumption (BLE TX with LDO: 10.6 mA @ 0 dBm, BLE RX with LDO: 8.8 mA @ 1.0 Mbps), good noise reduction and sensitivity.

### 1.2 Key Features

- Supply voltage: 1.8 V ~ 3.6 V
- Recommended voltage: 3.3 V
- Frequency: 2400.0 MHz ~ 2483.5 MHz
- Tx power: +7.0 dBm (@0 dBm)
- Sensitivity: -95.0 dBm
- Frequency error:  $\pm 20.0$  kHz
- Supply temperature range:  $-20.0$  °C ~  $+85.0$  °C
- Storage temperature range:  $-50.0$  °C ~  $+125.0$  °C
- ROM: 64.0 KB
- SRAM: 32.0 KB
- FLASH: 256.0 KB
- Outline dimension: 15.1 x 11.2 x (1.65  $\pm$  0.2) mm<sup>3</sup>

### 1.3 Application

- Smart toys
- Fitness equipment
- Environmental sensor nodes
- Passive key-less entry (PKE)
- Smart door locks
- Phone accessories
- Health-care equipment
- Smart lighting
- Energy harvesting
- Thermometer
- Human input devices
- Sports equipment
- Wearable

**1.4 Block Diagram**

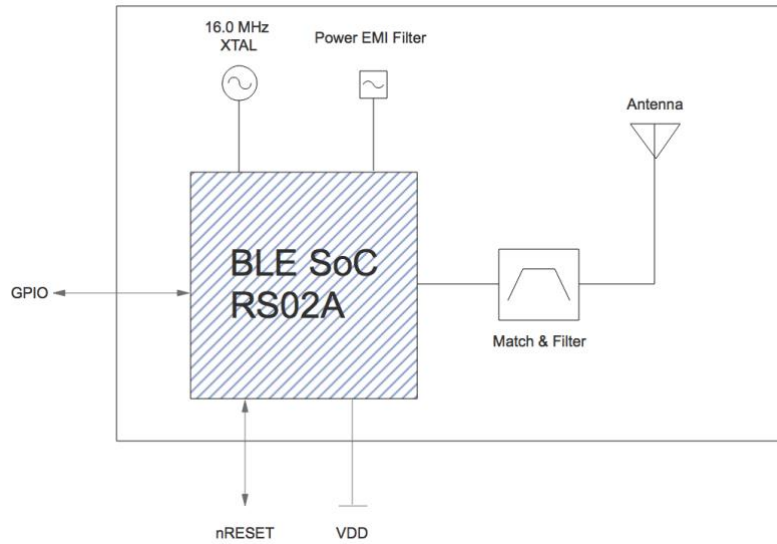


Figure 1. Block Diagram of NDB-M2658A

**1.5 Part Number Conventions**

The part numbers are of the form of NDB-M2658A where the fields are defined as follows.

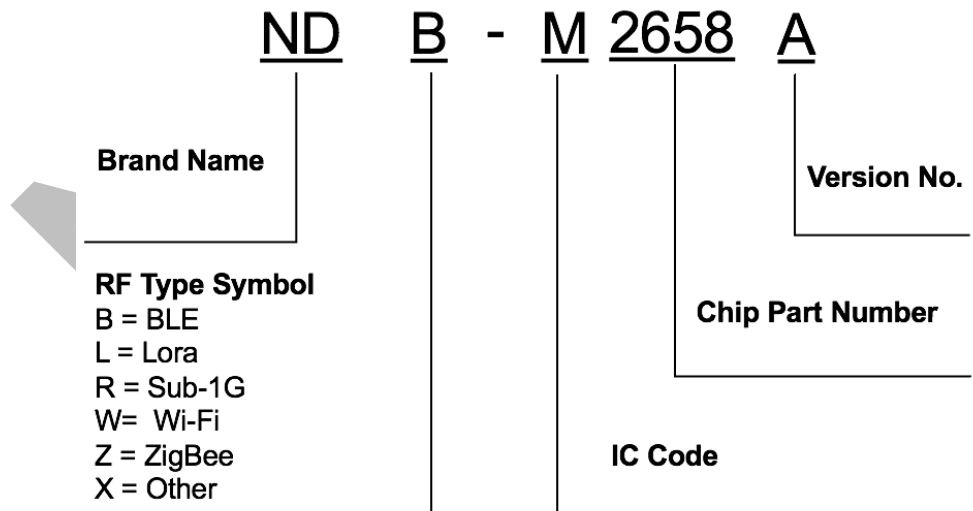


Figure 2. Part Number Conventions

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**2 Revision History**

NOTE: Pages number may be different from the former ones.

<b>Version No.:</b>	<b>Page</b>
• Changed Xx.....	Xx
• Added Xx .....	Xx

### 3 Terminal Configuration and Functions

#### 3.1 Pin Diagram

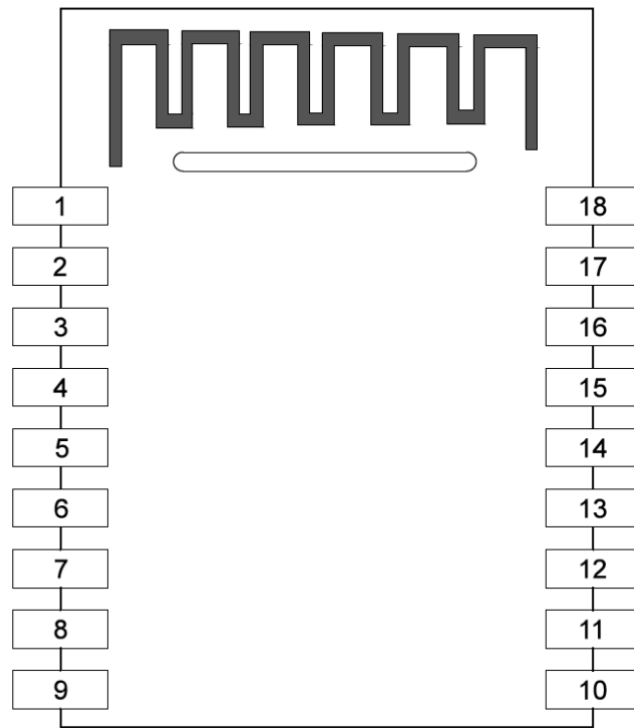


Figure 3. Pin Diagram of NDB-M2685A (Top View)

### 3.2 Pin Attributes

Table 1. Pin Attributes of NDB-M2685A

Pin	Name	Pin Type	Remarks
1	GND	Ground	Grounding
2	VCC	VCC	Power supply: 1.8 V ~ 3.6 V; Recommended: 3.3 V
3	P15	I/O	
4	P24	I/O	
5	RESET	RESTORE	Active when set low level
6	P06	I/O	
7	SWC	SWCLK	Connect the J-Link simulator SWCLK
8	SWD	SWDIO	Connect the J-Link simulator SWDIO
9	P21	I/O	
10	P10	I/O	
11	P11	I/O	
12	P12	I/O	
13	P14	I/O	
14	P16	I/O	
15	P17	I/O	
16	P27	I/O	
17	P28	I/O	
18	P03	I/O	

## 4 Mechanical and Packaging Information

### 4.1 Mechanical Drawing



Figure 4. Mechanical Drawing of NDB-M2658A

### 4.2 Recommended PCB Layout for Package

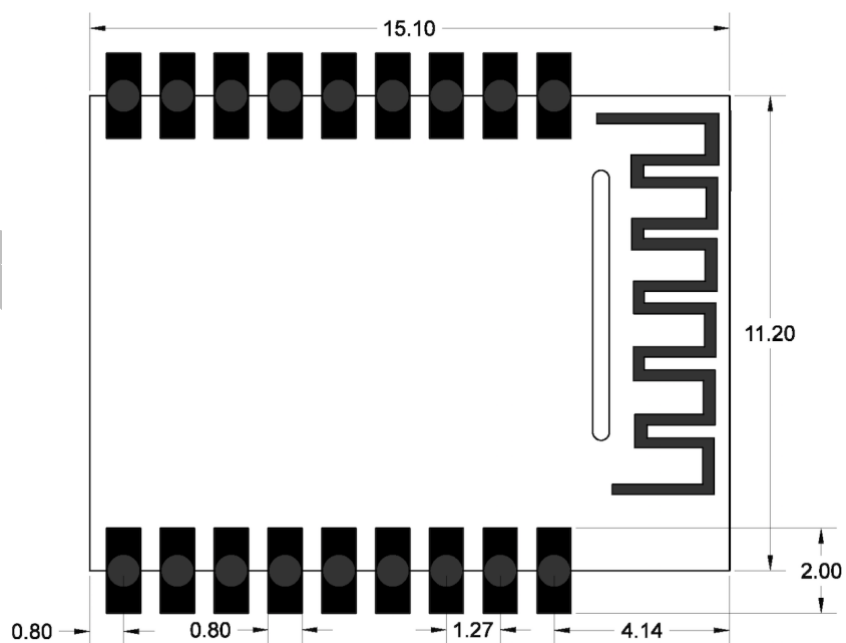


Figure 5. Recommended PCB Layout of NDB-2658A (mm)

## 5 Applications, Implementation, and Layout

### 5.1 Reference Schematics

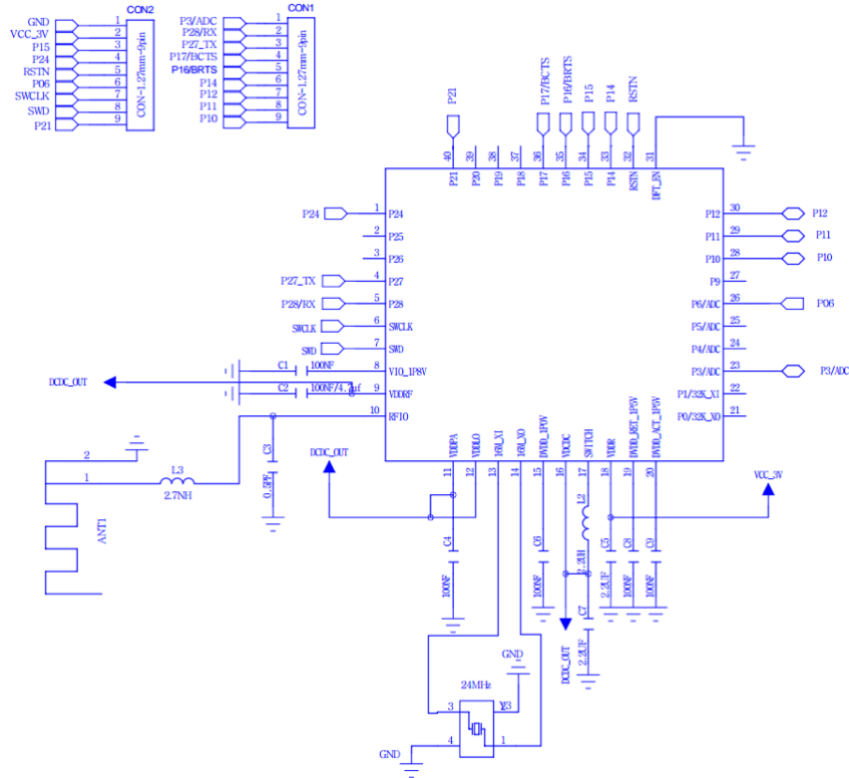


Figure 6. Reference Schematics

### 5.2 Soldering Recommendation

Recommended Reflow Profile for Lead Free Solder

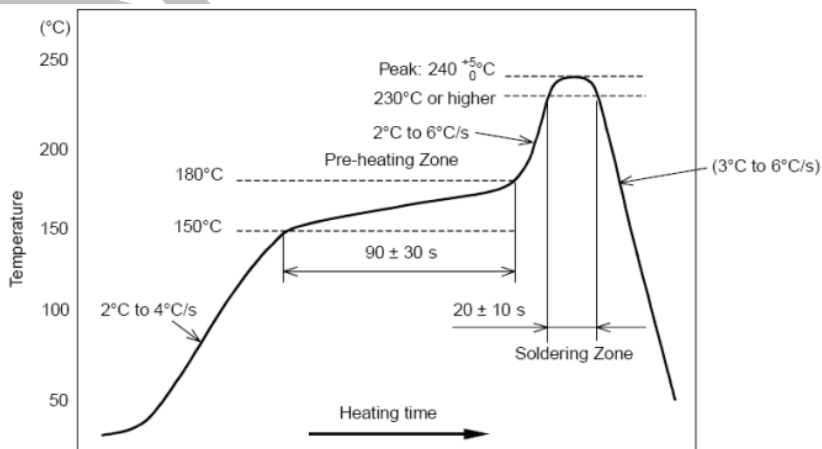


Figure 7. Recommended Reflow Profile for Lead Free Solder

## 6 Recommended Operating Conditions

### 6.1 Recommended Operation conditions

Notes :

- (1) The operating temperature is limited to the change of crystal's frequency;
- (2) To ensure the RF performance, the ripple wave on the source must be less than  $\pm 300$  mV

Identification	Condition	Min.	Typ.	Max.	Unit
Source & IO	Battery mode	1.6	3.3	3.6	V
Operating Temperature	/	-40	25	85	°C
Environmental Hot Pendulum		-20		20	°C / Min

### 6.2 Electrostatic Discharge Warnings

Module will be damaged for the discharge of static. Necdaz suggest that all modules should follow the 3 precautions below:

1. According to the anti-static measures, bare hands are not allowed to touch modules.
2. Modules must be placed in anti- static areas.
3. Take the anti-static circuitry (when inputting HV or VHF) into consideration in product design.

Static may result in the degradation in performance of module, even causing the failure.

## 7 Order Information

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